TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20131121000
Qualification of JCET Chuzhou as Additional Assembly/Test Site for SOT Package Devices
Change Notification / Sample Request

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

PCN# 20131121000
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20131121000	**PCN Date:**	11/22/2013

Title:	Qualification of JCET Chuzhou as Additional Assembly/Test Site for SOT Package Devices

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

Proposed 1st Ship Date:	02/22/2014	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Qualification of JCET Chuzhou as Additional Assembly/Test Site for DCY Package Devices. Material differences are shown in the following table:

	NFME	JCET Chuzhou
Mold Compound	SID# R-17	SID# 013101006201

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply

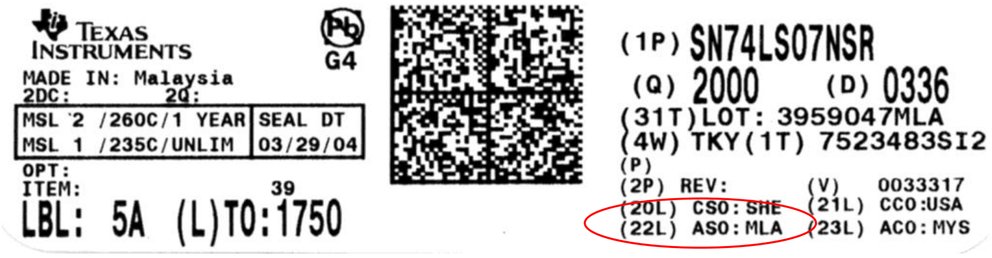
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
NFME	Assembly Site Origin (22L)	ASO: NS2
JCET Chuzhou	Assembly Site Origin (22L)	ASO: GP6

Sample product shipping label (not actual product label)



TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: NFME = E, JCET Chuzhou = F

Product Affected:

LM317DCYR	TLV1117-18CDCYRG3	TLV1117CDCYRG3	UA78M05IDCYR
LM317DCYRG3	TLV1117-18IDCYR	TLV1117IDCYR	UA78M05IDCYRG3
LM317MDCYR	TLV1117-18IDCYRG3	TLV1117IDCYRE3	UA78M33CDCYR
LM317MDCYRG3	TLV1117CDCYR	TLV1117IDCYRG3	UA78M33CDCYRG3
SN78MCDCYR	TLV1117CDCYR/2354	UA78M05CDCYR	
TLV1117-18CDCYR	TLV1117CDCYRE3	UA78M05CDCYRG3	

Qualification Data

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1 : LM317DCYR (MSL2-260C)

Package Construction Details

Assembly Site:	JCET CHUZHOU	Mold Compound:	013101006201
# Pins-Designator, Family:	4-DCY, SOT	Mount Compound:	011204001902
Lead Finish, Base	Matte Sn, Cu	Bond Wire:	2.0 Mil Dia. Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
Electrical Characterization	-	30/0	-	-
**Life Test	150C (300 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (192 Hrs)	77/0	77/0	77/0
**Temp Cycle, -65C/150C	1000 Cycles	77/0	77/0	77/0
**High Temp Storage Bake	170C (600 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 2 atm (192 Hrs)	77/0	77/0	77/0
Salt Atmosphere	24 Hrs	22/0	22/0	22/0
Solderability	Steam age, 8 hours; PB-Free solder	22/0	22/0	22/0
X-ray	(top side only)	5/0	5/0	5/0
Flammability (UL 94V-0)	(UL 94V-0)	5/0	5/0	5/0
Flammability (UL 94V-0)	(UL 94V-0)	5/0	5/0	5/0
Flammability (IEC 695-2-2)	(IEC 695-2-2)	5/0	5/0	5/0
Manufacturability Qualification (MQ)	(per mfg. Site specification)	Pass	-	-
Moisture Sensitivity	L2-260C	12/0	12/0	12/0

**- Preconditioning sequence: Level 2-260C.

Qual Vehicle 2 : TLV1117-18CDCYR (MSL2-260C)

Package Construction Details

Assembly Site:	JCET CHUZHOU	Mold Compound:	013101006201
# Pins-Designator, Family:	4-DCY, SOT	Mount Compound:	011204001902
Lead Finish, Base	Matte Sn, Cu	Bond Wire:	2.0 Mil Dia. Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
**Biased HAST	130C/85%RH (192 Hrs)	77/0	77/0	77/0
X-ray	(top side only)	5/0	5/0	5/0
Manufacturability Qualification (MQ)	(per mfg. Site specification)	Pass	-	-

**- Preconditioning sequence: Level 2-260C.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com